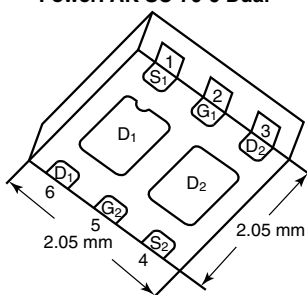


Dual N-Channel 12 V (D-S) MOSFET

PRODUCT SUMMARY

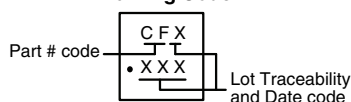
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a	Q_g (Typ.)
12	0.028 at $V_{GS} = 4.5$ V	4.5	6.2 nC
	0.033 at $V_{GS} = 2.5$ V	4.5	
	0.042 at $V_{GS} = 1.8$ V	4.5	

PowerPAK SC-70-6 Dual



Ordering Information: SiA910EDJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

Marking Code



FEATURES

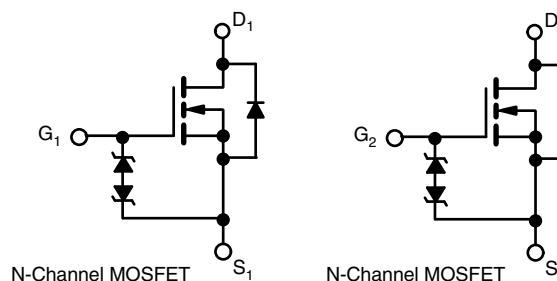
- TrenchFET[®] Power MOSFET
- Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area
 - Low On-Resistance
- Typical ESD Protection: 2400 V
- 100 % R_g Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load Switch for Portable Applications
- High Frequency DC/DC Converter
- DC/DC Converter



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	12	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	4.5 ^a
		$T_C = 70$ °C	4.5 ^a
		$T_A = 25$ °C	4.5 ^{a, b, c}
		$T_A = 70$ °C	4.5 ^{a, b, c}
Pulsed Drain Current	I_{DM}	20	A
Continuous Source-Drain Diode Current	I_S	$T_C = 25$ °C	4.5 ^a
		$T_A = 25$ °C	1.6 ^{b, c}
Maximum Power Dissipation	P_D	$T_C = 25$ °C	7.8
		$T_C = 70$ °C	5
		$T_A = 25$ °C	1.9 ^{b, c}
		$T_A = 70$ °C	1.2 ^{b, c}
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^{d, e}		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, f}	R_{thJA}	52	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	12.5	16	

Notes:

a. Package limited

b. Surface mounted on 1" x 1" FR4 board.

c. $t = 5$ s.

d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 110 °C/W.

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

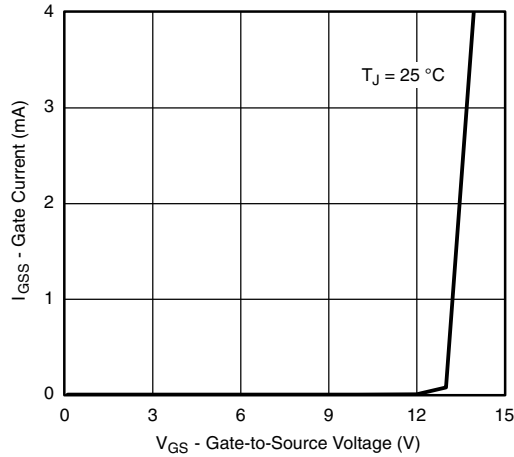
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	12			V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		8		mV/°C	
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 2.5			
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.4		1	V	
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 5	μA	
		V _{DS} = 0 V, V _{GS} = ± 4.5 V			± 0.5		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 12 V, V _{GS} = 0 V			1		
		V _{DS} = 12 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 4.5 V	10			A	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 5.2 A		0.023	0.028	Ω	
		V _{GS} = 2.5 V, I _D = 4.8 A		0.027	0.033		
		V _{GS} = 1.8 V, I _D = 2.5 A		0.035	0.042		
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 5.2 A		23		S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{DS} = 6 V, V _{GS} = 0 V, f = 1 MHz		455		pF	
Output Capacitance	C _{oss}			190			
Reverse Transfer Capacitance	C _{rss}			150			
Total Gate Charge	Q _g	V _{DS} = 6 V, V _{GS} = 8 V, I _D = 6.8 A		10.5	16	nC	
Gate-Source Charge	Q _{gs}	V _{DS} = 6 V, V _{GS} = 4.5 V, I _D = 6.8 A		6.2	9.5		
Gate-Drain Charge	Q _{gd}			0.8			
Gate Resistance	R _g			1.6			
Turn-On Delay Time	t _{d(on)}	f = 1 MHz	0.8	4	8	Ω	
Rise Time	t _r		V _{DD} = 6 V, R _L = 1.1 Ω I _D ≅ 5.4 A, V _{GEN} = 4.5 V, R _g = 1 Ω		10	15	ns
Turn-Off Delay Time	t _{d(off)}				12	20	
Fall Time	t _f				25	40	
Turn-On Delay Time	t _{d(on)}			12	20		
Rise Time	t _r	V _{DD} = 6 V, R _L = 1.1 Ω I _D ≅ 5.4 A, V _{GEN} = 10 V, R _g = 1 Ω		5	10		
Turn-Off Delay Time	t _{d(off)}			10	15		
Fall Time	t _f			20	30		
				10	15		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			4.5	A	
Pulse Diode Forward Current	I _{SM}				20		
Body Diode Voltage	V _{SD}	I _S = 5.4 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	I _F = 5.4 A, dI/dt = 100 A/μs, T _J = 25 °C		25	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			10	20	nC	
Reverse Recovery Fall Time	t _a			13		ns	
Reverse Recovery Rise Time	t _b			12			

Notes:

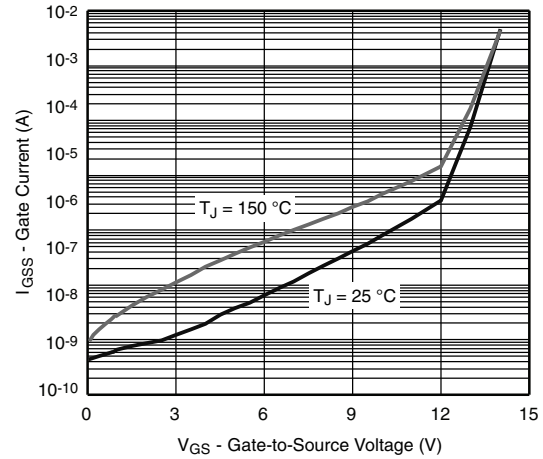
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

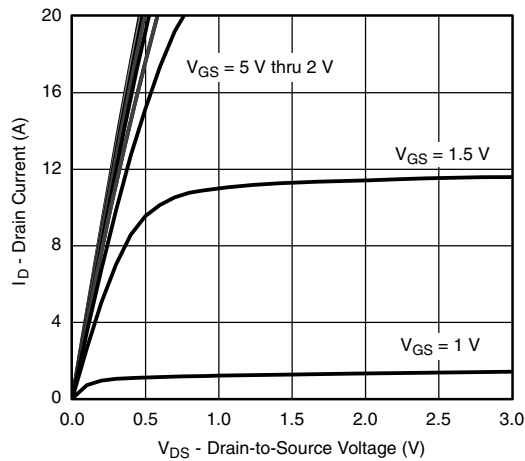
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



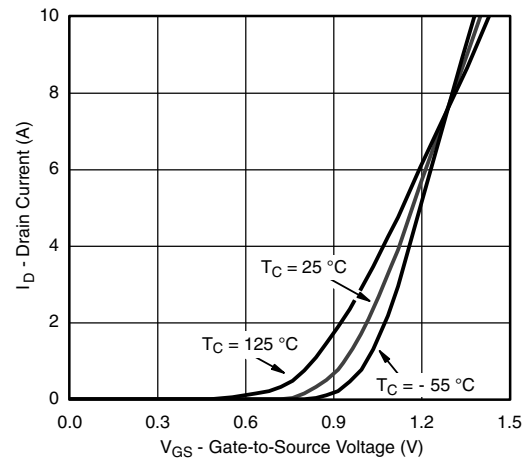
Gate Current vs. Gate-Source Voltage



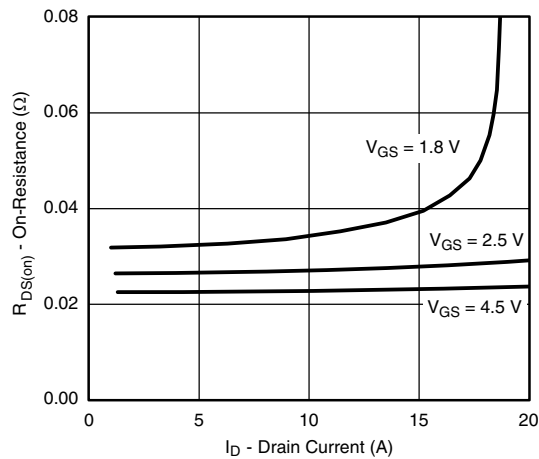
Gate Current vs. Gate-Source Voltage



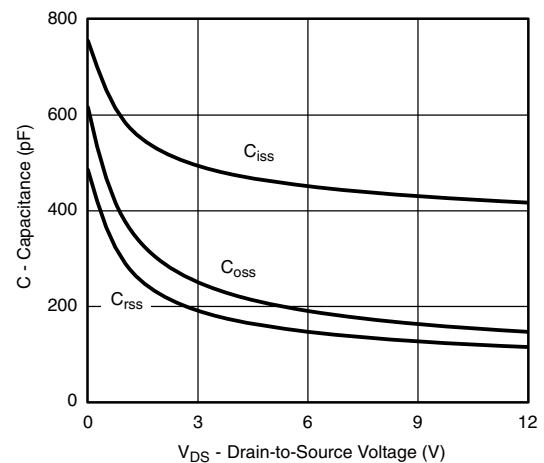
Output Characteristics



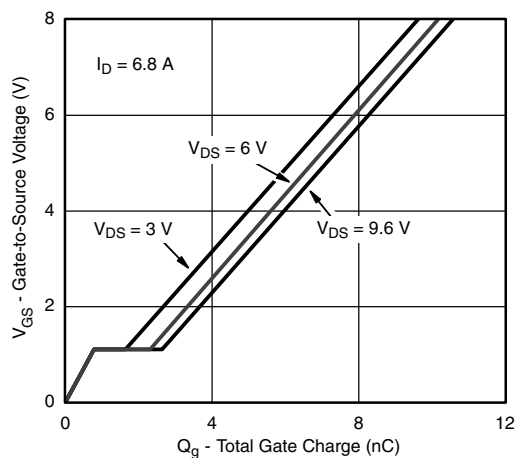
Transfer Characteristics



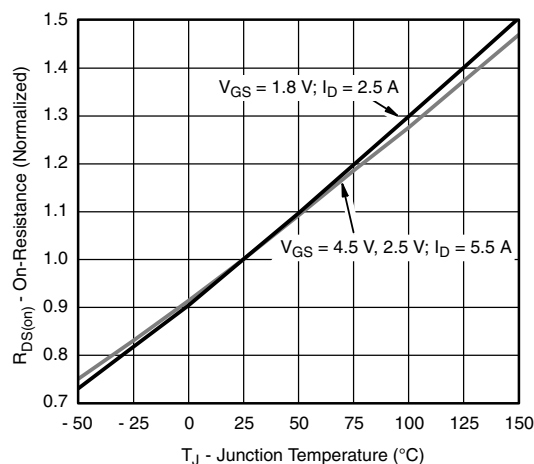
On-Resistance vs. Drain Current and Gate Voltage



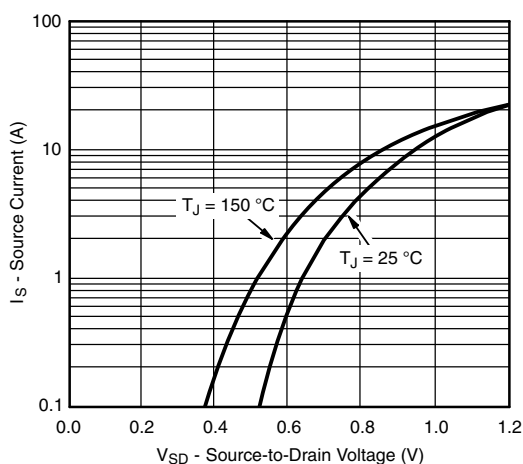
Capacitance

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

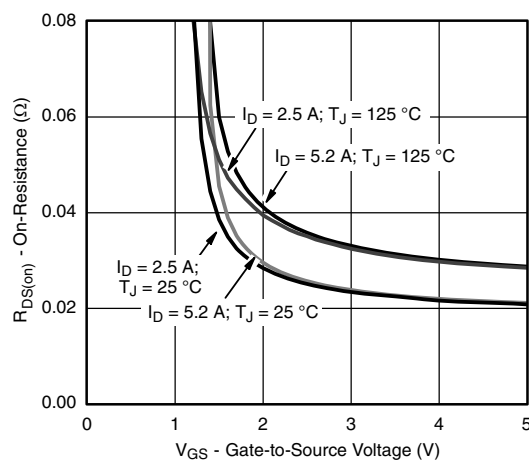
Gate Charge



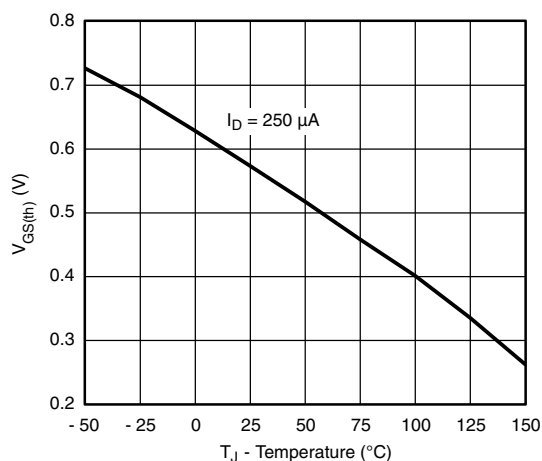
On-Resistance vs. Junction Temperature



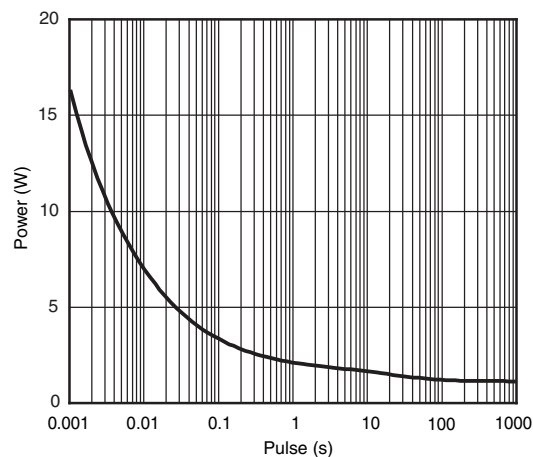
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

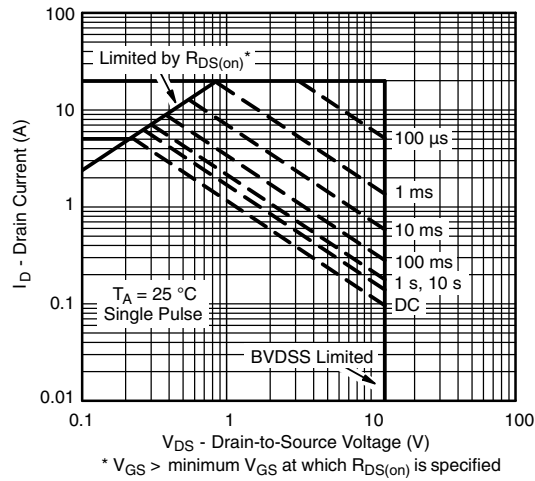


Threshold Voltage

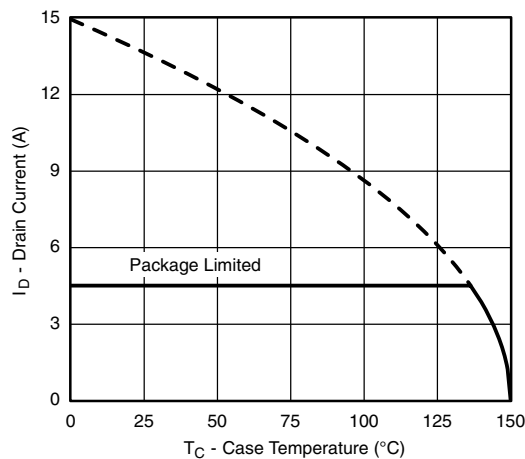


Single Pulse Power (Junction-to-Ambient)

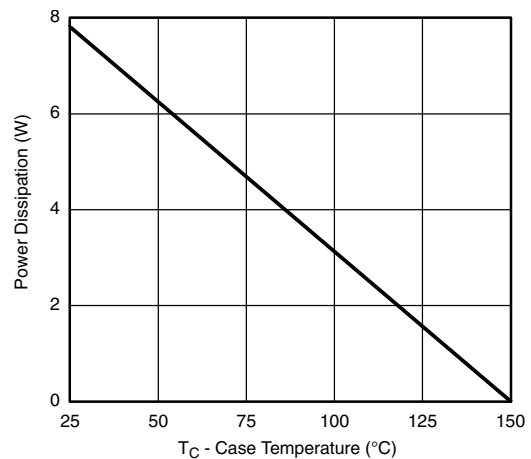
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient

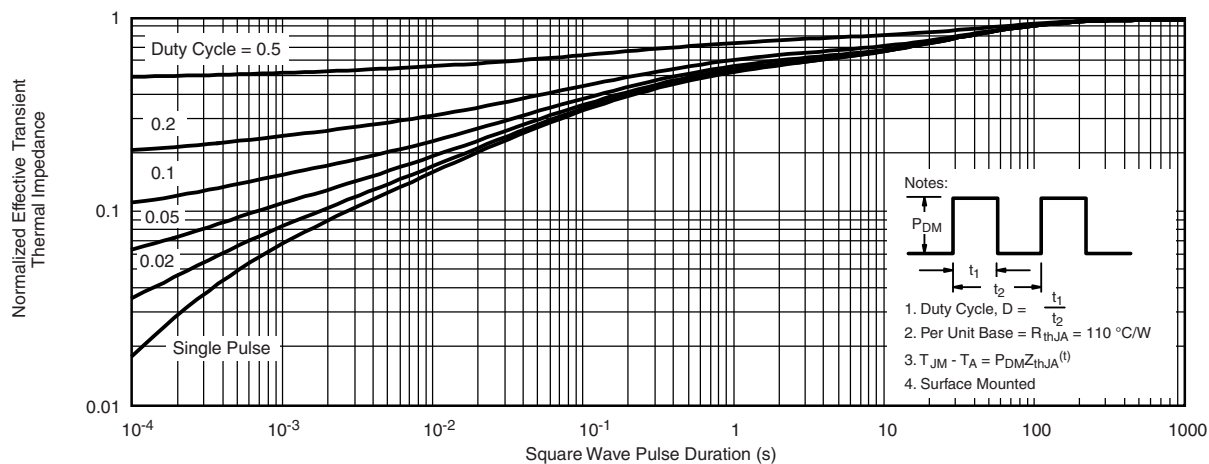
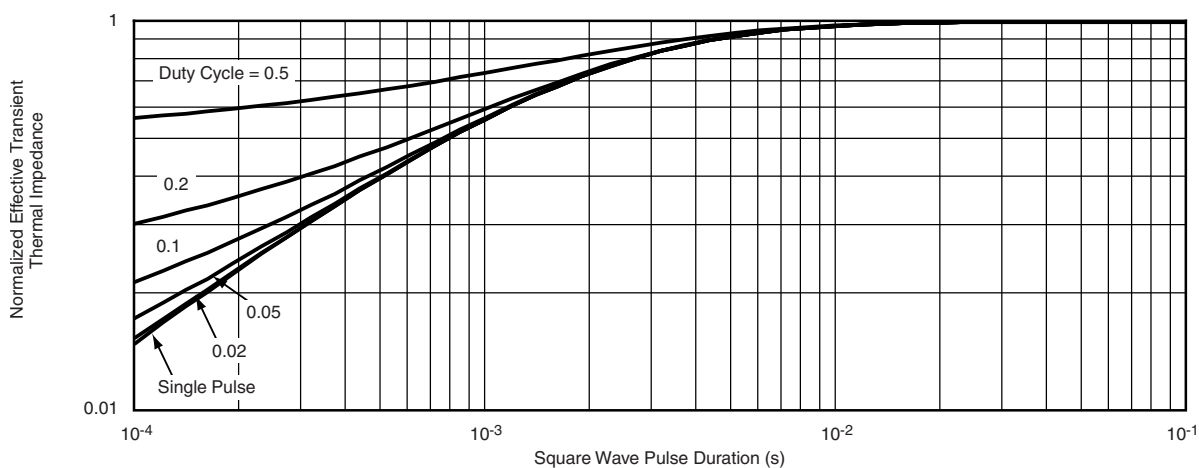


Current Derating*



Power Derating

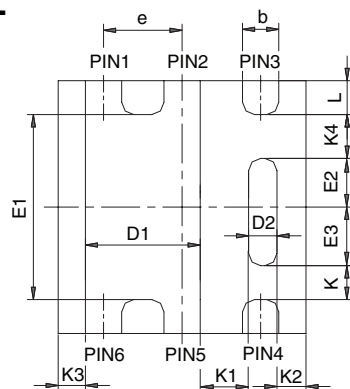
* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Case**

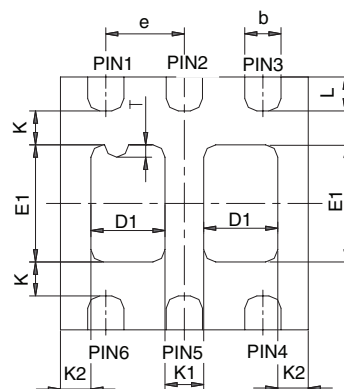
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?65535.



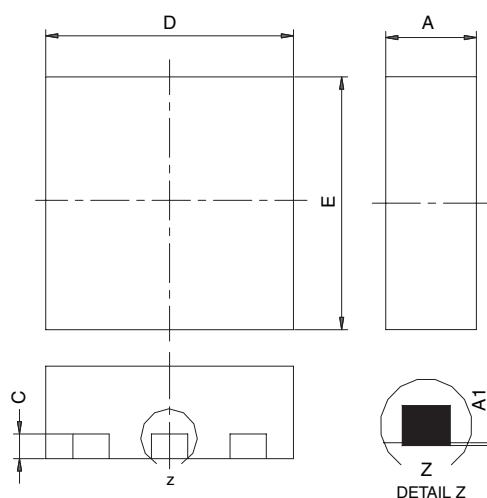
PowerPAK® SC70-6L



BACKSIDE VIEW OF SINGLE



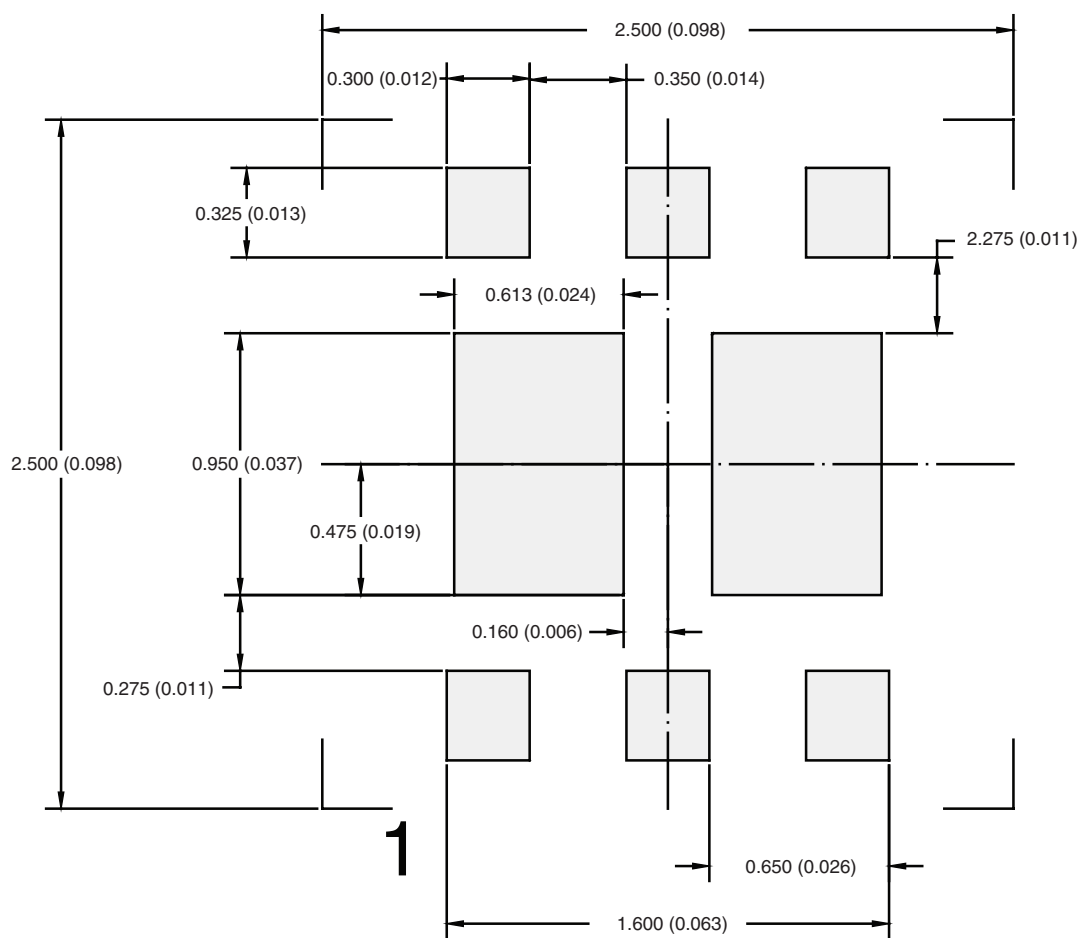
BACKSIDE VIEW OF DUAL



- Notes:
1. All dimensions are in millimeters
 2. Package outline exclusive of mold flash and metal burr
 3. Package outline inclusive of plating

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006
ECN: C-07431 – Rev. C, 06-Aug-07												
DWG: 5934												

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm/(Inches)



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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